

1. (Currently Amended) A bonding pad for electrically bonding a magnetic head terminal comprising a metal pad having a bonding substance applied as a surface finishing material and heat treated prior to bonding the bonding pad to a surface.
2. (Original) A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein said bonding substance is solder.
3. (Original) A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a conductive polymer.
4. (Original) A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein said bonding substance is an adhesive.
5. (Original) A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a film.
6. (Previously Amended) A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 2, wherein a bump height for the solder is approximately 50-300  $\mu\text{m}$ , and a bump diameter for the solder is less than 180  $\mu\text{m}$ .
7. (Currently Amended) A disk drive comprising:

a bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material and heat treated prior to bonding the bonding pad to a surface.

8. (Original) The disk drive as claim in claim 7, wherein said bonding substance is solder.

9. (Original) The disk drive as claim in claim 7, wherein said bonding substance is a conductive polymer.

10. (Original) The disk drive as claim in claim 7, wherein said bonding substance is an adhesive.

11. (Original) The disk drive as claim in claim 7, wherein said bonding substance is a film.

12. (Previously Amended) The disk drive as claim in claim 8, wherein a bump height for the solder is approximately 50-300  $\mu\text{m}$ , and a bump diameter for the solder is less than 180  $\mu\text{m}$ .